

Tamperproof Sticker for e-Passports

e-Sticker to easily convert standard passport booklets into e-Passport booklets or to be used also as e-Visa sticker • STK01

- ▶ Proven design ensures optimum chip performance
- ▶ Available with the widest selection of contactless IC chips from leading suppliers
- ▶ Sticker design and format size allows for easy customization
- ▶ Inlay sticker adheres to virtually any material or surface
- ▶ Complies with ICAO and ISO standards



SECURE identification.

Designed to convert conventional passports (travel documents) into ICAO-compliant electronic passports, HID Global's STK01 contactless inlay sticker enables secure contactless identification to be incorporated into any passport card or data page. A reliable and highly secure solution, the inlay stickers reduce authentication errors and falsification of documentation. Available with a choice of contactless e-Passport ICs from the leading chip suppliers, the STK01 sticker inlays accommodate a wide range of customer requirements and proven modules types.

Constructed using HID Global's proprietary ceFLEX™ material, the inlay stickers are extremely durable and guarantee full protection of the electronic chip and antenna. Offering exceptional adhesion to a wide range of materials and surfaces, including Polycarbonate and other plastic materials, the tamper-proof sticker inlays are able to withstand daily mechanical wear and are optimized for use in the e-Passport manufacturing process.

- ▶ Sticker contains an ICAO-compliant, ID1 size proximity transponder
- ▶ Antenna module connected through thermo-compression process
- ▶ Multiple uses like for ePassports, e-Visa, e-ID card, etc.
- ▶ Sticker inlays are performance tested for durability
- ▶ Offer the widest range of carrier materials available to guarantee flexibility in design and excellent durability
- ▶ Available with a choice of contactless e-Passport ICs
- ▶ Durable inlay material provides advanced document resiliency (10 years)

Specifications

Available with different IC's	<p>Chip: Available with a choice of contactless e-Passport IC's from leading chip suppliers based on customer requirements within different proven module types (e.g. MOB4, MCC8, etc.)</p> <p>Operating system: ICAO conform OS according to customer preference</p>
Dimensions	<p>Format: One sticker with transponders 100% functional tested</p> <p>Width and length: 122 mm x 80 mm ± 0.5 mm (customized formats possible)</p> <p>Thickness: Final thickness is depending on provided security paper (Typical: 0.6 mm ± 0.05 mm including release paper on adhesive layer)</p>
Material	<p>Intermediate layers: ceFLEX-PI</p> <p>Front layers: customized printed security paper (supplied by customer)</p> <p>Adhesive layer: ceFLEX-P8 (protected by release layer)</p>
Electrical	<p>Operating frequency: 13.56 MHz</p> <p>Resonance frequency: 15.3 MHz – 1.9 MHz</p> <p>Data transfer: up to 848 kbits/s (depending on IC and reader)</p>
Antenna	<p>Size: ID1</p> <p>Material: Copper wire (Ø 100 µm)</p> <p>Module connection: Thermo-compression bonding</p> <p>Technology: transfer wire technology, patented by HID Global</p>
Storage conditions	<p>Recommended temperature: +15° C to +30° C</p> <p>Recommended humidity: 40% - 70% rel. humidity</p>
Operating conditions	<p>Recommended temperature: 15° C to +60° C</p> <p>Thermal resistance: - 35°C to +85°C (acc. ICAO 9303¹)</p>
Adhesion	Tamperproof
Certifications	<p>ISO 9001:2000 certifications for the manufacturing sites</p> <p>Common Criteria EAL5+ for chip</p> <p>Common Criteria EAL4+ for operating system</p> <p>ROHS conformity 2002/95/EG</p>
Resistance	<p>The sticker is designed to resist common stress known for e-passports</p> <p>Dynamic Bending stress: 1000 cycles (ISO/IEC 10373)</p> <p>Dynamic torsion stress: 1000 cycles (ISO/IEC 10373, ICAO 9303¹)</p> <p>Impact test: 25 cycles each side; 250 g at 320 mm height (HID test standard)</p> <p>Chemical: according to ICAO 9303¹</p> <p>UV exposure: according to ICAO 9303¹</p> <p>X-Ray exposure: according to ICAO 9303¹</p>
	<p>This sticker has been qualified successfully by passport manufacturers through demanding internal test procedures exceeding ISO and ICAO requirements.</p> <p>HID is constantly reviewing the test procedure based on ICAO recommendations.</p>

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SECURE identity.

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